

2SK940

FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE (L²-π-MOSIII)

HIGH SPEED SWITCHING APPLICATIONS.
RELAY DRIVE, MOTOR DRIVE AND DC-DC CONVERTER APPLICATIONS.

- . 4-Volt Gate Drive
- . Low Drain-Source ON Resistance : $R_{DS(ON)}=0.4\Omega(\text{Typ.})$
- . High Forward Transfer Admittance : $|Y_{fs}| = 0.75S(\text{Typ.})$
- . Low Leakage Current : $I_{GSS}=\pm 3\mu A(\text{Max.})$ @ $V_{GS}=\pm 16V$
 $I_{DSS}=300\mu A(\text{Max.})$ @ $V_{DS}=60V$
- . Enhancement-Mode : $V_{th}=0.8\sim 2.0V$ @ $V_{DS}=10V, I_D=1mA$

MAXIMUM RATINGS (Ta=25°C)

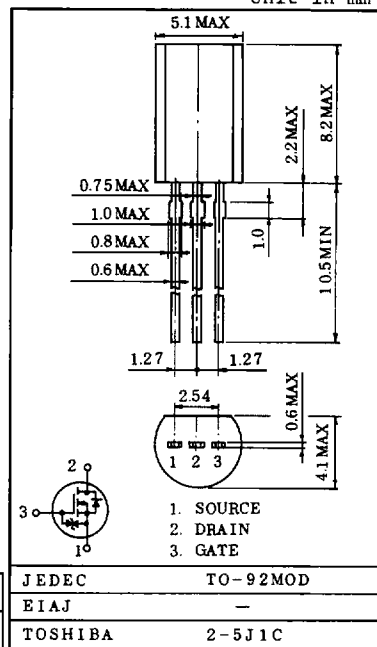
| CHARACTERISTIC | | SYMBOL | RATING | UNIT |
|---|-------|-----------|----------|------|
| Drain-Source Voltage | | V_{DSS} | 60 | V |
| Drain-Gate Voltage ($R_{GS}=20k\Omega$) | | V_{DGR} | 60 | V |
| Gate-Source Voltage | | V_{GSS} | ± 20 | V |
| Drain Current | DC | I_D | 0.8 | A |
| | Pulse | I_{DP} | 2.4 | |
| Drain Power Dissipation (Ta=25°C) | | P_D | 0.9 | W |
| Channel Temperature | | T_{ch} | 150 | °C |
| Storage Temperature Range | | T_{stg} | -55~150 | °C |

THERMAL CHARACTERISTICS

| CHARACTERISTIC | SYMBOL | MAX. | UNIT |
|--|----------------|------|------|
| Thermal Resistance, Channel to Ambient | $R_{th(ch-a)}$ | 138 | °C/W |

INDUSTRIAL APPLICATIONS

Unit in mm



Weight : 0.36g

ELECTRICAL CHARACTERISTICS (Ta=25°C)

| CHARACTERISTIC | | SYMBOL | TEST CONDITION | MIN. | TYP. | MAX. | UNIT |
|---|---------------|----------|-------------------------|------|------|------|------|
| Gate Leakage Current | | IGSS | VGS=±16V, VDS=0V | - | - | ±3 | μA |
| Drain Cut-off Current | | IDSS | VDS=60V, VGS=0V | - | - | 300 | μA |
| Drain-Source Breakdown Voltage | | V(BR)DSS | ID=10mA, VGS=0V | 60 | - | - | V |
| Gate Threshold Voltage | | Vth | VDS=10V, ID=1mA | 0.8 | - | 2.0 | V |
| ON State Drain Current | | ID(ON) | VDS=4V, VGS=4V | 0.8 | - | - | A |
| Drain-Source ON Resistance | | RDS(ON) | VGS=4V, ID=0.4A | - | 0.75 | 1.1 | Ω |
| | | | VGS=10V, ID=0.4A | - | 0.40 | 0.55 | |
| Forward Transfer Admittance | | Yfs | VDS=10V, ID=0.4A | 0.50 | 0.75 | - | S |
| Input Capacitance | | Ciss | VDS=10V, VGS=0V, f=1MHz | - | 95 | 140 | pF |
| Reverse Transfer Capacitance | | Crss | | - | 25 | 50 | |
| Output Capacitance | | Coss | | - | 65 | 110 | |
| Switching Time | Rise Time | tr | | - | 4 | 15 | ns |
| | Turn-on Time | ton | | - | 9 | 25 | |
| | Fall Time | tf | | - | 25 | 60 | |
| | Turn-off Time | toff | | - | 55 | 120 | |
| Total Gate Charge (Gate-Source Plus Gate-Drain) | | QG | ID=0.8A, VGS=10V | - | 3.3 | 6.6 | nC |
| Gate-Source Charge | | Qgs | VDD=48V | - | 1.9 | - | |
| Gate-Drain ("Miller") Charge | | Qgd | | - | 1.4 | - | |

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta=25°C)

| CHARACTERISTIC | SYMBOL | TEST CONDITION | MIN. | TYP. | MAX. | UNIT |
|----------------------------------|--------|------------------|------|------|------|------|
| Continuous Drain Reverse Current | IDR | - | - | - | 0.8 | A |
| Pulse Drain Reverse Current | IDRP | - | - | - | 2.4 | A |
| Diode Forward Voltage | VDSF | IDR=0.8A, VGS=0V | - | -0.9 | -1.5 | V |
| Reverse Recovery Time | trr | IDR=0.8A, VGS=0V | - | 90 | - | ns |
| Reverse Recovered Charge | Qrr | dIDR/dt=20A/μs | - | 35 | - | nC |